

**REVISIONS**

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED

REV																				
SHEET																				
REV																				
SHEET	15	16	17	18	19	20	21	22	23											

REV STATUS OF SHEETS	REV																		
	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14				

<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A	PMIC N/A	PREPARED BY Larry T. Gauder	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		
		CHECKED BY Monica L. Poelking			
		APPROVED BY Monica L. Poelking	MICROCIRCUIT, DIGITAL, BTL 9-BIT LATCHING DATA TRANSCEIVER, MONOLITHIC SILICON		
		DRAWING APPROVAL DATE 95-01-06			
		REVISION LEVEL	SIZE <b>A</b>	CAGE CODE <b>67268</b>	<b>5962-95542</b>
		SHEET 1	OF	23	

DESC FORM 193  
JUL 94

5962-E066-95

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

■ 9004708 0009853 219 ■



1.3 Absolute maximum ratings. 1/

Supply voltage ( $V_{CC}$ )	- - - - -	6.5 V
Control input voltage	- - - - -	6.5 V
Driver input and receiver output	- - - - -	5.5 V
Bus termination voltage	- - - - -	2.4 V
Receiver input current	- - - - -	±15 mA
Storage temperature range ( $T_{STG}$ )	- - - - -	-65°C to +150°C
Maximum power dissipation ( $P_{SD}$ ) 2/	- - - - -	1.7 W
Lead temperature (soldering, 4 seconds)	- - - - -	+260°C
Junction temperature ( $T_J$ )	- - - - -	+175°C
Thermal resistance, junction-to-case ( $\theta_{JC}$ )	- - - - -	See MIL-STD-1835
Thermal resistance, junction-to-ambient ( $\theta_{JA}$ )	- - - - -	87 C/W

1.4 Recommended operating conditions.

Supply voltage range ( $V_+$ )	- - - - -	+4.5 V dc to +5.5 V
Bus termination voltage ( $V_t$ )	- - - - -	2.06 V to 2.14 V
Ambient operating temperature range ( $T_A$ )	- - - - -	-55°C to +125°C

1.5 Digital logic testing for device classes Q and V.

Fault coverage measurement of manufacturing logic tests (MIL-STD-883, test method 5012) - - - - - 3/ XX percent

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, bulletin, and handbook. Unless otherwise specified, the following specification, standards, bulletin, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.  
 MIL-STD-973 - Configuration Management.  
 MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

HANDBOOK

MILITARY

MIL-HDBK-780 - Standardized Military Drawings.

(Copies of the specification, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ Derate at 11.5 mW/ C above +25 C.
- 3/ Values will be added when they become available.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>	5962-95542
	REVISION LEVEL	SHEET 3

DESC FORM 193A  
 JUL 94

9004708 0009855 091

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not effect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Truth table. The truth table shall be as specified on figure 3.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 4.

3.2.5 Test circuits and switching waveforms. The test circuits and switching waveforms shall be as specified on figure 5.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes Q and V shall be in accordance with MIL-I-38535.

3.5.1 Certification/compliance mark. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-I-38535.

3.6 Certificate of compliance. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.2 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.1 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M, the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

3.9 Verification and review for device class M. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 100 (see MIL-I-38535, appendix A).

### 4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device class M, sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein). For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 or as modified in the device manufacturer's QM plan. The modification in the QM plan shall not effect the form, fit, or function as described herein.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95542
		REVISION LEVEL	SHEET 4

DESC FORM 193A  
JUL 94

9004708 0009856 T28

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C V <sub>CC</sub> = 5 V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Driver and control inputs: (CD, T/R, An, ACLK, LE and RBYP)							
Logical 1 input voltage	V <sub>IH</sub>		1, 2, 3	01	2		V
Logical 0 input voltage	V <sub>IL</sub>		1, 2, 3	01		0.8	V
Input leakage current	I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 5.5 V	1, 2, 3	01		100	μA
Input high current	I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 2.4 V An = CD = 0.5 V, T/R = 2.4 V	1, 2, 3	01		40	μA
Input low current	I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = An = CD = 0.5 V T/R = 2.4 V	1, 2, 3	01		-100	μA
Input diode clamp voltage	V <sub>IC</sub>	V <sub>CC</sub> = 4.5 V, I <sub>CLAMP</sub> = -12 mA	1, 2, 3	01		-1.2	V

Driver output/receiver input: (Bn)

Output low bus voltage	V <sub>OLB</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 80 mA, CD = 0.5 V, An = T/R = 2.4 V 1/	1, 2	01	0.75	1.10	V
			3		0.75	1.15	
Output low bus current	I <sub>OLBZ</sub>	V <sub>CC</sub> = 5.5 V, An = 0.5 V CD = 0 V, BN = 0.75 V, T/R = 2.4 V	1, 2, 3	01		-100	μA
Output high bus current	I <sub>OHBZ</sub>	V <sub>CC</sub> = 5.5 V, An = 0.5 V, CD = 0 V, BN = 2.1 V, T/R = 2.4 V	1, 2, 3	01		100	μA
Receiver input threshold	V <sub>TH</sub>	T/R = CD = 0.5 V	1, 2, 3	01	1.47	1.62	V

See footnotes at end of table.

STANDARD  
MICROCIRCUIT DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-95542

REVISION LEVEL

SHEET

5

DESC FORM 193A  
JUL 94

9004708 0009857 964

TABLE I. Electrical performance characteristics. - continued

Test	Symbol	Conditions -55°C ≤ T <sub>c</sub> ≤ +125°C V <sub>CC</sub> = 5V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Positive clamp diode voltage	V <sub>CLP</sub>	V <sub>CC</sub> = 5.5 or 0 V, I <sub>Bn</sub> = 1 mA	1, 2, 3	01	2.0	4.6	V
		V <sub>CC</sub> = 5.5 or 0 V, I <sub>Bn</sub> = 10 mA	1, 2, 3		2.6	5.1	
Negative clamp diode voltage	V <sub>CLN</sub>	V <sub>CC</sub> = 5.5 V, I <sub>clamp</sub> = -12 mA	1, 2, 3	01		-1.2	V

Receiver output: (AN)

Logical 1 output voltage	V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, B <sub>n</sub> = 1.1 V I <sub>OH</sub> = -2 mA, T/ $\bar{R}$ =CD=0.5 V	1, 2, 3	01	2.4		V
Logical 0 output voltage	V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V, B <sub>n</sub> = 2.1 V I <sub>OL</sub> = 8 mA, T/ $\bar{R}$ =CD=0.5 V	1, 2, 3	01		0.4	V
		V <sub>CC</sub> = 4.5 V, B <sub>n</sub> = 2.1 V I <sub>OL</sub> = 24 mA, T/ $\bar{R}$ =CD=0.5 V				0.5	
TRI-STATE leakage current	I <sub>OZ</sub>	V <sub>CC</sub> = 5.5 V, CD = 2.4 V, B <sub>n</sub> = 0.75 V, V <sub>IN</sub> = 2.4 V, T/ $\bar{R}$ = 0.5 V	1, 2, 3	01		40	μA
		V <sub>CC</sub> = 5.5 V, CD = 2.4 V, B <sub>n</sub> = 0.75 V, V <sub>IN</sub> = 0.5 V, T/ $\bar{R}$ = 0.5 V				-100	
Output short circuit current	I <sub>OS</sub>	V <sub>CC</sub> = 5.5 V, B <sub>n</sub> = 1.1 V, T/ $\bar{R}$ = CD = 0.5 V <u>2/</u>	1, 2, 3	01	-40	-100	mA
Functional test		V <sub>CC</sub> = 4.5 V to 5.5 V See 4.4.1b	7,8				

See footnotes at end of table.

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		<b>REVISION LEVEL</b>	<b>SHEET 6</b>

DESC FORM 193A  
JUL 94

■ 9004708 0009858 8TD ■

TABLE I. Electrical performance characteristics. - continued

Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C V <sub>CC</sub> = 5 V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Supply current							
Supply current includes V <sub>CC</sub>	I <sub>CCT</sub>	V <sub>CC</sub> = 5.5 V, CD = 0.5 V, T/R = An = ACLK = RBYP = LE = 3.4 V	1, 2, 3	01		70	mA
Supply current for a TTL high input	I <sub>CC</sub>	T/R = CD = 0.5 V, Bn = 2.1V ACLK = RBYP = LE = 0.5 V	1, 2, 3	01		60	mA
Live insertion current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5 V, T/R = An = CD = ACLK = 0.5 V	1, 2, 3	01		6	mA
		V <sub>CC</sub> = 5.5 V, CD = ACLK = 0.5 V T/R = AN = RBYP = 2.4 V				3	
Driver							
An to Bn propagation delay fall-through mode	t <sub>PHLA</sub>	CD = 0 V, RL = 12.5 ohms RBYP = T/R = 3 V C <sub>L</sub> = 30 pF	9, 10, 11	01	1	8	ns
An to Bn propagation delay fall-through mode	t <sub>PLHA</sub>	CD = 0 V, RL = 12.5 ohms T/R = RBYP = 3 V C <sub>L</sub> = 30 pF	9, 10, 11	01	1	8	ns
ACLK to Bn propagation delay latch mode	t <sub>PHLCK</sub>	CD = RBYP = 0 V, T/R = 3 V, RL = 12.5 ohms C <sub>L</sub> = 30 pF	9, 10, 11	01	1	9	ns
ACLK to Bn propagation delay latch mode	t <sub>PLHCK</sub>	CD = RBYP = 0 V, T/R = 3 V, RL = 12.5 ohms C <sub>L</sub> = 30 pF	9, 10, 11	01	1	8	ns
CD to Bn enable time	t <sub>PHLCD</sub>	An = 3 V, T/R = 3 V, C <sub>L</sub> = 30 pF, RL = 12.5 ohms	9, 10, 11	01	2	12	ns
CD to Bn disable time	t <sub>PLHCD</sub>	An = 3 V, T/R = 3 V, C <sub>L</sub> = 30 pF, RL = 12.5 ohms	9, 10, 11	01	2	9	ns
T/R to Bn enable time	t <sub>PHLTR</sub>	CD = 0 V, RBYP = 3 V	9, 10, 11	01	8	25	ns
T/R to Bn: disable time	t <sub>PLHTR</sub>	CD = 0 V, RBYP = 3 V	9, 10, 11	01	3	12	ns
STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444				SIZE A			5962-95542
					REVISION LEVEL	SHEET 7	

DESC FORM 193A  
JUL 94

9004708 0009859 737

TABLE 1. Electrical performance characteristics. - continued

Test	Symbol	Conditions -55°C ≤ T <sub>c</sub> ≤ +125°C V <sub>CC</sub> = 5 V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Driver (continued)							
Transition time 20% to 80%	t <sub>r</sub>	CD = RBYP = 0 V, T/R = 3 V, CL = 30 pF, RL = 12.5 ohms	9, 10, 11	01	1	4	ns
Transition time 80% to 20%	t <sub>f</sub>	CD = RBYP = 0 V, T/R = 3 V, CL = 30 pF, RL = 12.5 ohms	9, 10, 11	01	1	4	ns
Slew rate	S <sub>R</sub>	from 1.3 to 1.8 V CD = RBYP = 0 V, T/R = 3 V	9, 10, 11	01	1		ns
Skew between drivers in the same package	t <sub>skewD</sub>	An to Bn	9, 10, 11	01		5	ns
		ACLK to Bn				5	
Driver timing requirements							
An to ACLK setup time	t <sub>sD</sub>		9, 10, 11	01		3	ns
An to ACLK hold time	t <sub>hD</sub>		9, 10, 11	01		3	ns
ACLK pulse width	t <sub>pwD</sub>		9, 10, 11	01		3	ns
Receiver							
Bn to An propagation delay bypass mode	t <sub>PHLB</sub>	LE = 3 V, CD = T/R = 0 V C <sub>L</sub> = 50 pF, RL = 1K ohms	9, 10, 11	01	2	9	ns
Bn to An propagation delay bypass mode	t <sub>PLHB</sub>	LE = 3 V, CD = T/R = 0 V C <sub>L</sub> = 30 pF	9, 10, 11	01	2	9	ns
LE to An propagation delay latch mode	t <sub>PHLLE</sub>	CD = T/R = 0 V, RL = 1 K C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
LE to An propagation delay latch mode	t <sub>PLHLE</sub>	CD = T/R = 0 V, C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
See footnotes at end of table.							
<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>				<b>SIZE A</b>		5962-95542	
						REVISION LEVEL	

DESC FORM 193A  
JUL 94

9004708 0009860 459



TABLE I. Electrical performance characteristics. - continued

Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C V <sub>CC</sub> = 5 V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Receiver (continued)							
CD to An disable time	t <sub>PLZCD</sub>	LE = 3 V, Bn = 2.1 V, T/R = 0 V, RL = 500 ohms, C <sub>L</sub> = 50 pF	9, 10, 11	01	1	18	ns
CD to An enable time	t <sub>PZLCD</sub>	LE = 3 V, Bn = 2.1 V, T/R = 0 V, RL = 500 ohms, C <sub>L</sub> = 50 pF	9, 10, 11	01	3	13	ns
CD to An disable time	t <sub>PHZCD</sub>	LE = 3 V, Bn = 1.1 V, T/R = 0 V, RL = 500 ohms, C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
CD to An enable time	t <sub>PZHCD</sub>	Bn = 1.1 V, T/R = 0 V, RL = 500 ohms, C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
T/R to An disable time	t <sub>PLZTR</sub>	LE = 3 V, CD = 0 V	9, 10, 11	01	3	18	ns
T/R to An enable time	t <sub>PZLTR</sub>	LE = 3 V, CD = 0 V	9, 10, 11	01	3	18	ns
Disable time	t <sub>PHZTR</sub>	LE = 3 V, CD = 0 V Bn = 1.1 V, RL = 500 ohms C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
T/R to An enable time	t <sub>PZHTR</sub>	LE = 3 V, CD = 0 V Bn = 1.1 V, RL = 500 ohms C <sub>L</sub> = 50 pF	9, 10, 11	01	3	11	ns
Skew between receivers in the same package	t <sub>skewR</sub>	Bn to An <u>3/</u>	9, 10, 11	01		5	ns
		LE to An				5	

See footnotes at end of table.

STANDARD  
MICROCIRCUIT DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-95542

REVISION LEVEL

SHEET

9

DESC FORM 193A  
JUL 94

■ 9004708 0009861 395 ■

TABLE I. Electrical performance characteristics. - continued

Test	Symbol	Conditions -55°C ≤ T <sub>v</sub> ≤ +125°C V <sub>CC</sub> = 5 V ± 10% unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Receiver timing requirements							
Bn to LE setup time	t <sub>sBn</sub>	CD = T/R̄ = 0 V	9, 10, 11	01		3	ns
LE to Bn hold time	t <sub>hLE</sub>	CD = T/R̄ = 0 V	9, 10, 11	01		3	ns
LE pulse width	t <sub>pwLE</sub>	CD = T/R̄ = 0 V	9, 10, 11	01		3	ns

- 1/ Referenced to appropriate signal ground. Do not exceed maximum power dissipation of package.
- 2/ Only one output at a time should be shorted and duration of short not to exceed one second.
- 3/ t<sub>sKEH</sub> is an absolute value defined as differences seen in propagation delays between drivers/receivers in the same package.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95542
		REVISION LEVEL	SHEET 10

DESC FORM 193A  
JUL 94

■ 9004708 0009862 221 ■

Case X

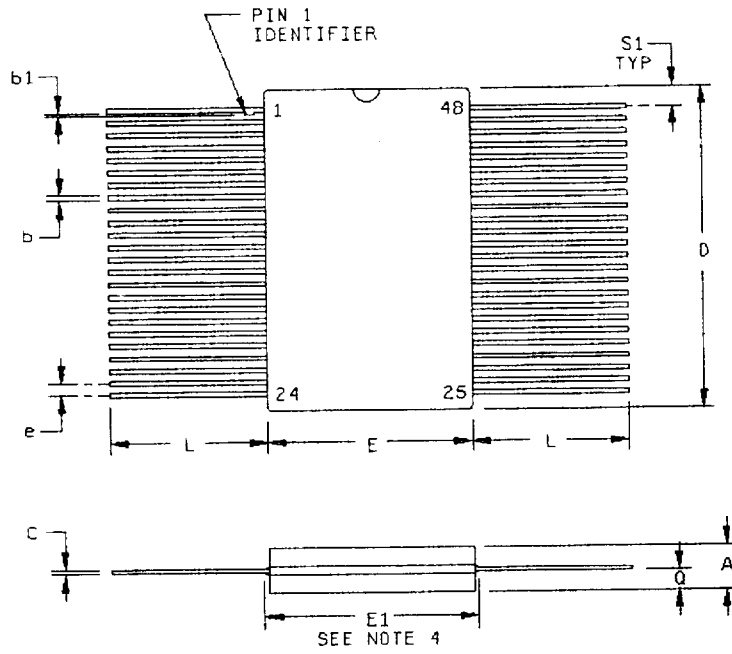


FIGURE 1. Case outline.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-95542
		REVISION LEVEL	SHEET 11

DESC FORM 193A  
 JUL 94

9004708 0009863 168

Dimensions	Millimeters		Inches		Notes
	Min	Max	Min	Max	
A	1.78	2.54	.070	.100	
b	0.20	0.30	.008	.012	
b1	0.08	0.18	.003	.007	
c	0.10	0.23	.004	.009	
D		16.26		.640	
e	0.64 BSC		.025 BSC		
E	9.55	9.75	.376	.384	
E1		10.16		.400	4
L	6.35	8.89	.250	.350	
Q	0.79	1.14	.031	.045	5
S1	0.13		.005		

**NOTES:**

1. The preferred unit of measurement is millimeters. However, this item was designed using inch-pound units of measurements. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
2. Lead number 1 is identified by a tab located on the lead.
3. Lead numbers are shown for reference only and do not appear on package.
4. Dimensions E1 allow for glass meniscus.
5. Dimension Q shall be measured at the point of exit of the lead from the body.

FIGURE 1. Case outline.- continued

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		<b>REVISION LEVEL</b>	<b>SHEET 12</b>

DESC FORM 193A  
JUL 94

■ 9004708 0009864 0T4 ■

Device type	All	Device type	All
Case outline	X	Case outline	X
Terminal number	Terminal symbol	Terminal number	Terminal symbol
1	NC	25	NC
2	LI	26	NC
3	NC	27	RBYP
4	Q GND	28	ACLK
5	LE	29	B8 GND
6	V <sub>CC</sub>	30	B8
7	A0	31	B7
8	NC	32	B7 GND
9	A1	33	B6 GND
10	A2	34	B6
11	A3	35	B5
12	GND	36	B5 GND
13	A4	37	B4 GND
14	Q V <sub>CC</sub>	38	B4
15	V <sub>CC</sub>	39	B3
16	A5	40	B3 GND
17	A6	41	B2 GND
18	A7	42	NC
19	A8	43	B2
20	T/ $\bar{R}$	44	B1
21	CD	45	B1 GND
22	GND	46	B0 GND
23	NC	47	B0
24	NC	48	NC

FIGURE 2. Terminal connections.

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		<b>REVISION LEVEL</b>	<b>SHEET 13</b>

DESC FORM 193A  
JUL 94

■ 9004708 0009865 T30 ■

CD	T/R	LE	RBYP	ACLK	An	Bn*
H	X	X	X	X	Z	H
L	H	X	H	X	L	H
L	H	X	H	X	H	L
L	H	X	L	X	X	Bn <sub>0</sub>
L	H	X	L	L-H	H	L
L	H	X	L	L-H	L	H
L	L	H	X	X	H	L
L	L	H	X	X	L	H
L	L	L	X	X	An <sub>0</sub>	X

\* = Assumed to be pulled up to 2.1 V.  
 X = High or low logic state.  
 Z = High impedance state.  
 L = Low state.  
 H = High state.  
 L-H = Low to high transition.  
 An<sub>0</sub> = No change from previous state.  
 Bn<sub>0</sub> = No change from previous state.  
 For BTL, high and low state is nominally 2.1 V and 1.0 V, respectively.  
 For BTL, high and low state is nominally 2.4 V and 0.5 V, respectively.

FIGURE 3. Truth table.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>		5962-95542
		REVISION LEVEL	SHEET 14

DESC FORM 193A  
 JUL 94

■ 9004708 0009866 977 ■

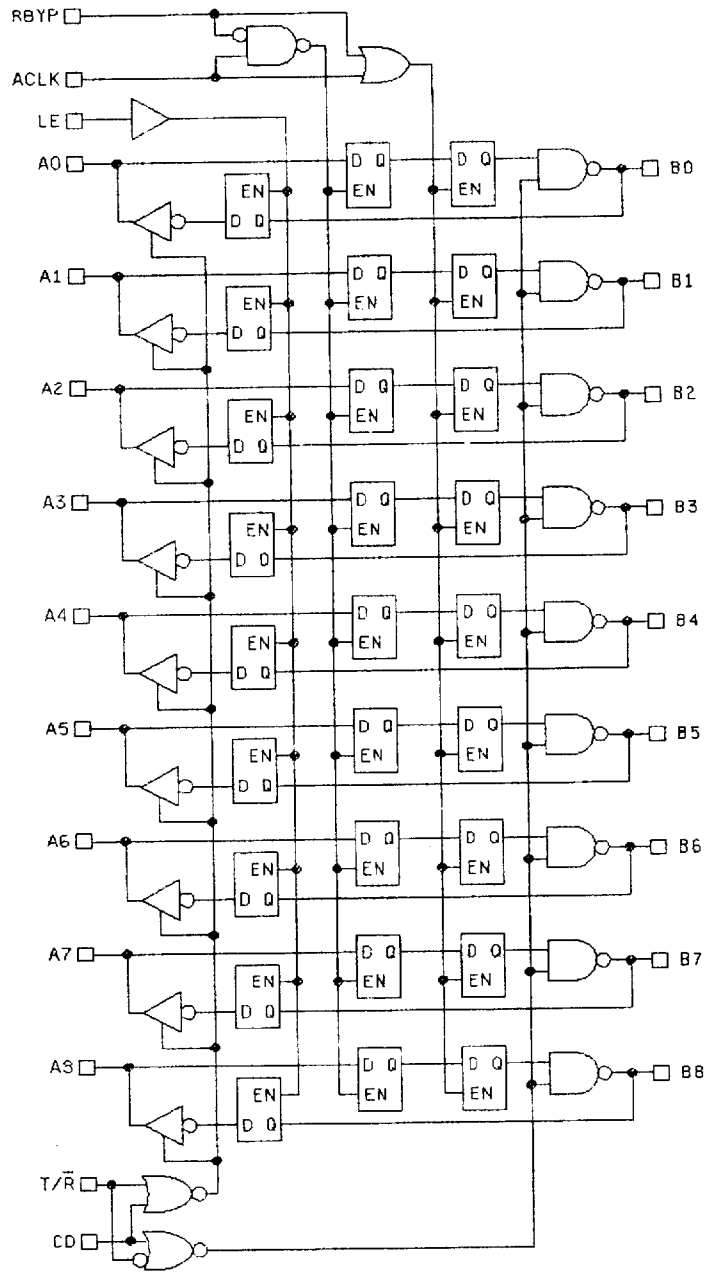
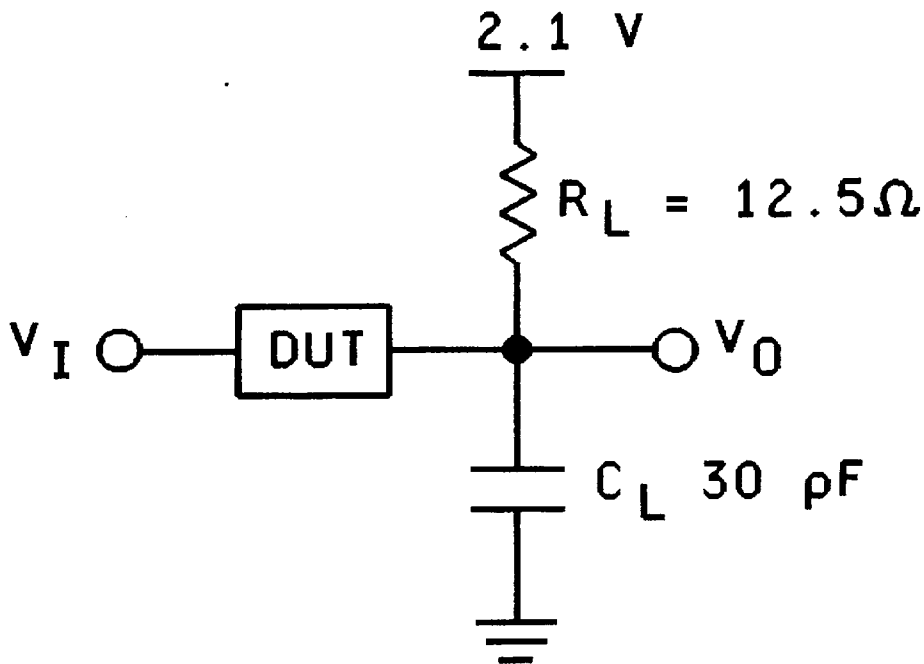


FIGURE 4. Logic diagram.

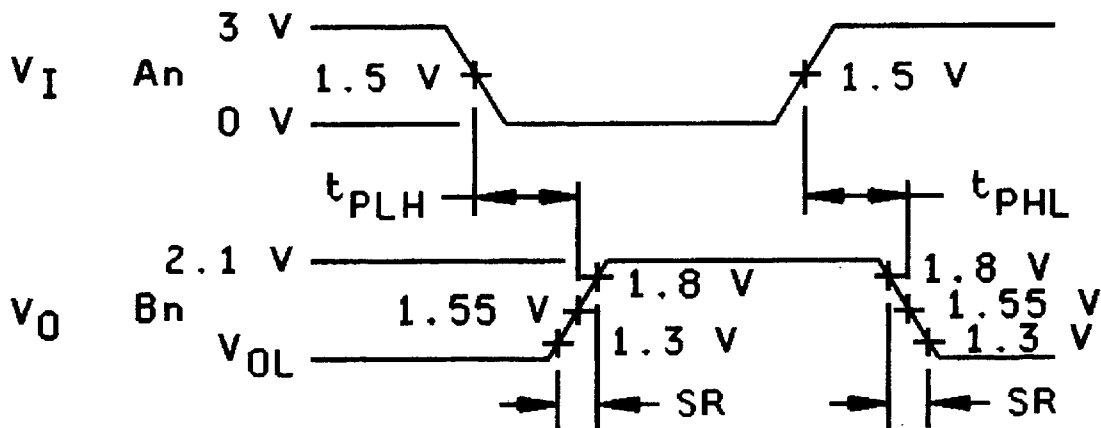
STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>	5962-95542
		REVISION LEVEL SHEET 15

DESC FORM 193A  
 JUL 94

■ 9004708 0009867 803 ■



Driver propagation delay set-up



Driver: An to Bn, SR

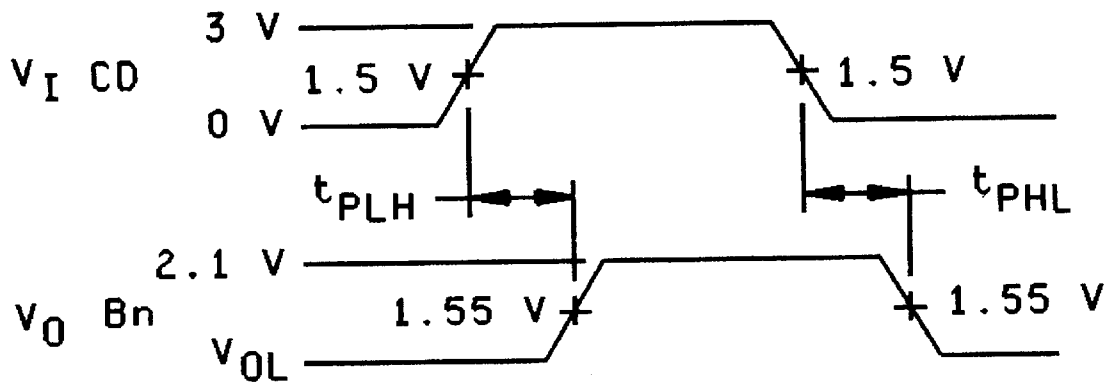
FIGURE 5. Test circuits and switching waveforms.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>		5962-95542
		REVISION LEVEL	SHEET 16

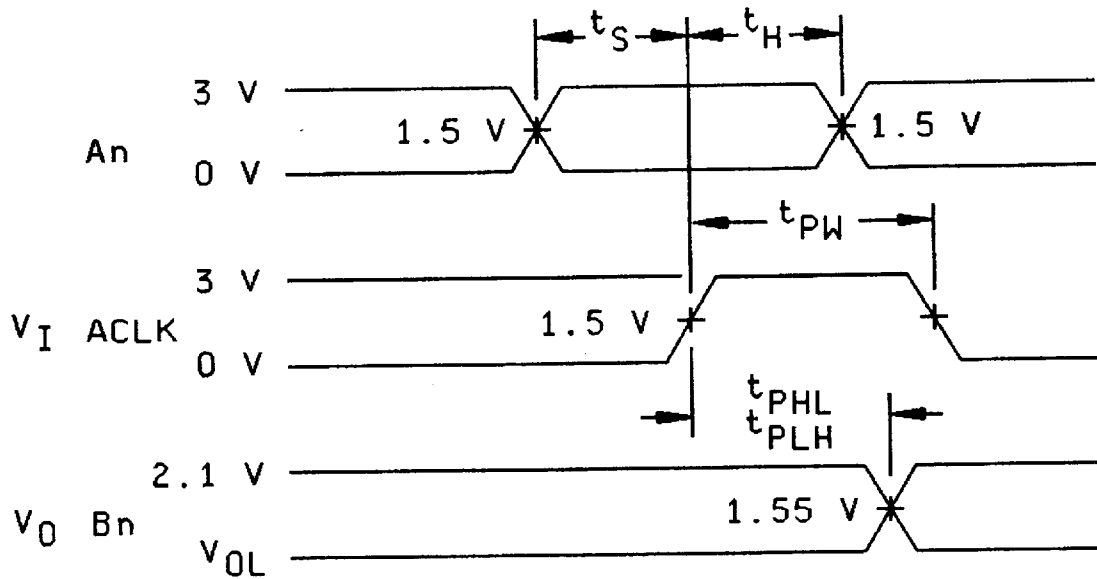
DESC FORM 193A  
 JUL 94

■ 9004708 0009868 74T ■

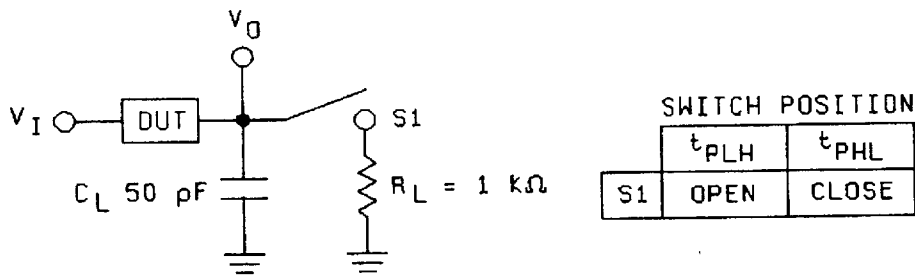




Driver: CD to Bn



Driver: ACLK to Bn,  $t_S$ ,  $t_H$ ,  $t_{PW}$



Receiver propagation delay set-up

FIGURE 5. Test circuits and switching waveforms. - continued

STANDARD  
MICROCIRCUIT DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-95542

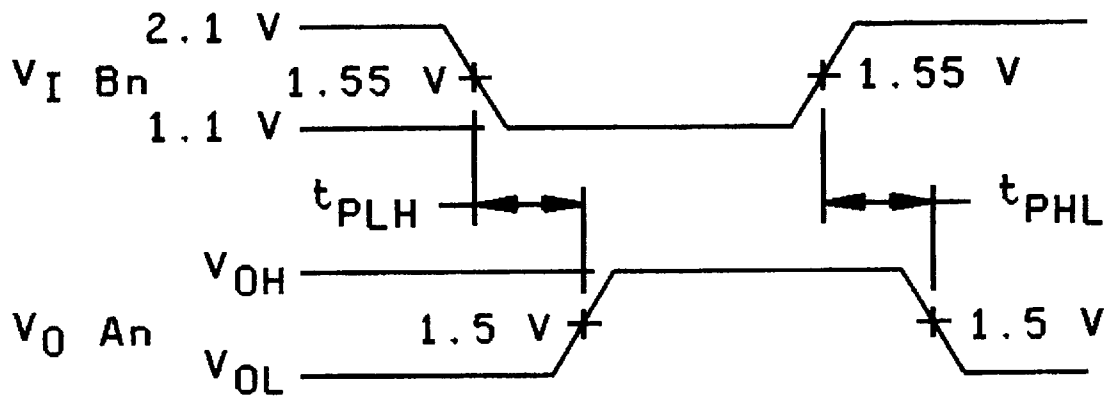
REVISION LEVEL

SHEET

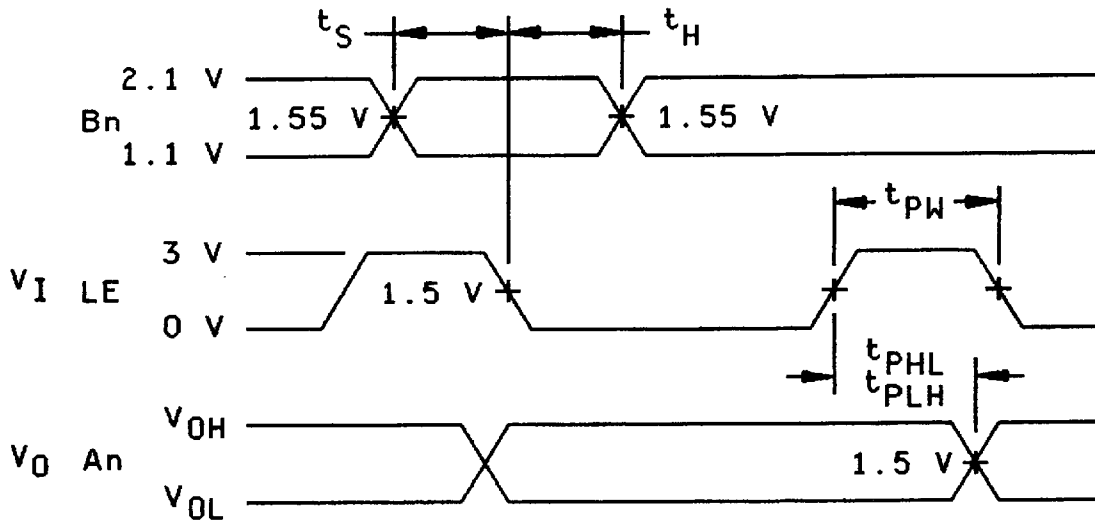
17

DESC FORM 193A  
JUL 94

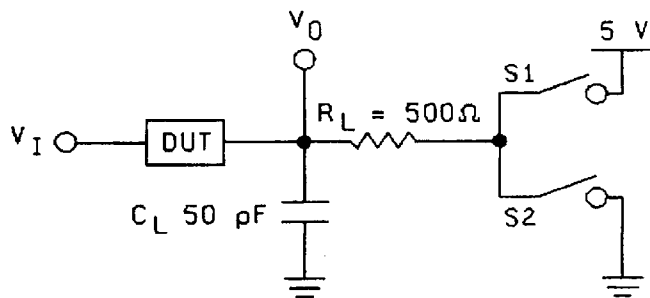
9004708 0009869 686



Receiver: Bn to An



Receiver: LE to An,  $t_S$ ,  $t_H$ ,  $t_{PW}$



		SWITCH POSITION	
		$t_{PZL}$ $t_{PLZ}$	$t_{PZH}$ $t_{PHZ}$
S1	CLOSE		OPEN
S2	OPEN		CLOSE

Receiver enable/disable set-up  
FIGURE 5. Test circuits and switching waveforms. - continued

STANDARD  
MICROCIRCUIT DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

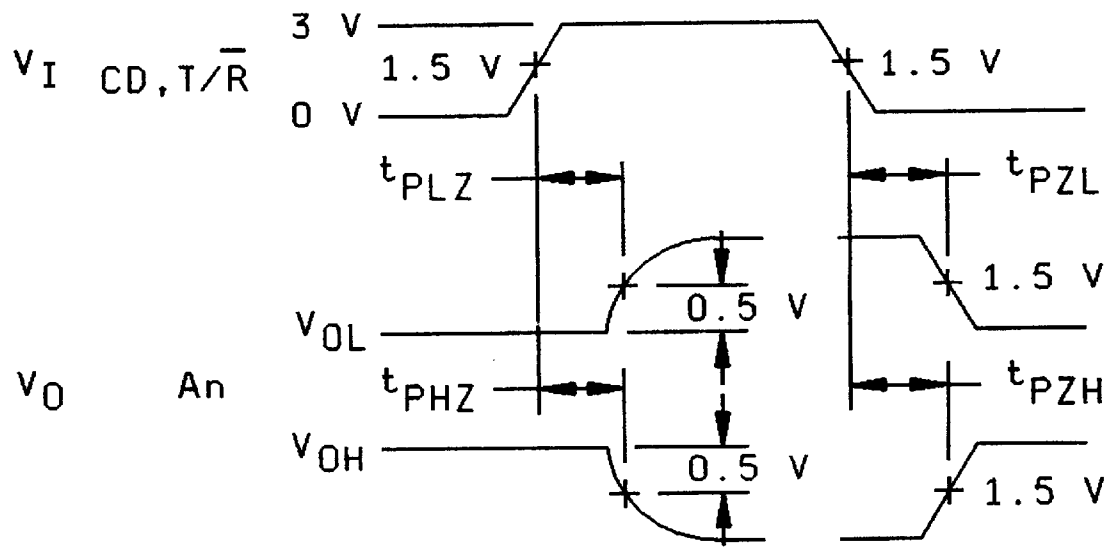
SIZE  
A

5962-95542

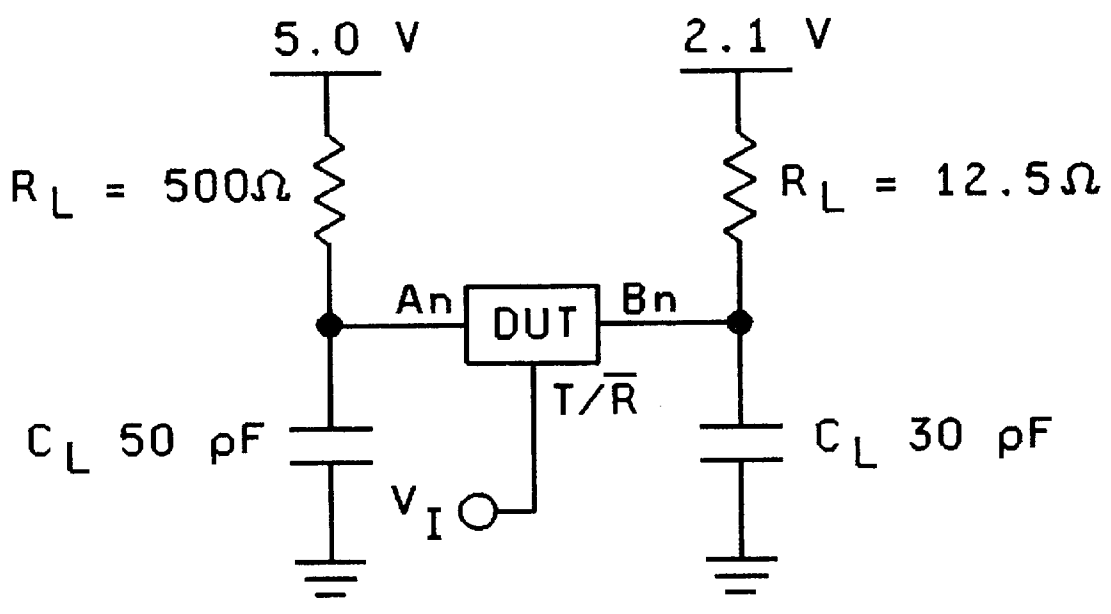
REVISION LEVEL

SHEET

18



Receiver: CD to An,  $T/\bar{R}$  to An ( $t_{PHZ}$  and  $t_{PZH}$  only)



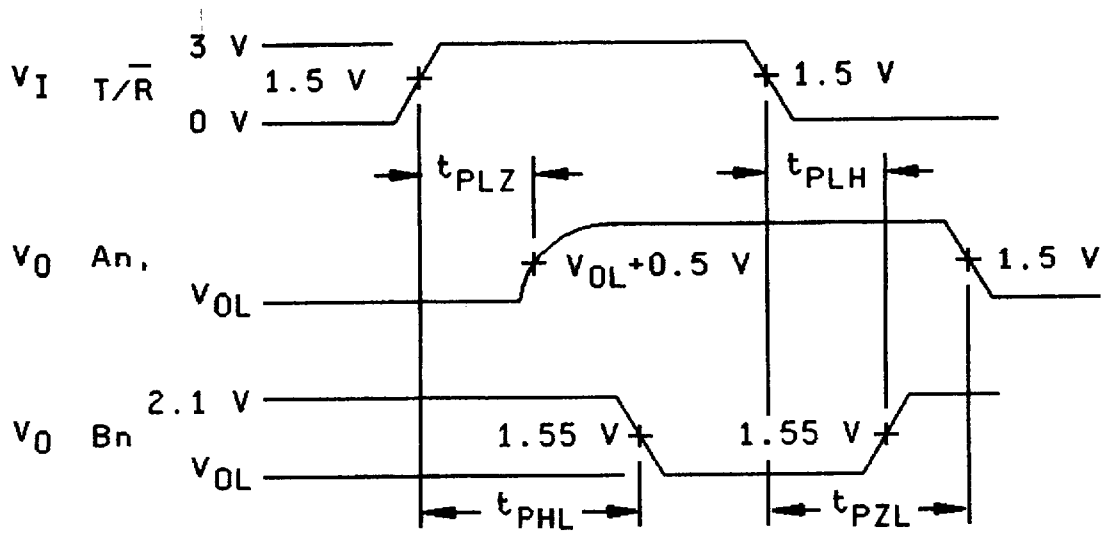
$T/\bar{R}$  to An,  $T/\bar{R}$  to Bn

FIGURE 5. Test circuits and switching waveforms. - continued

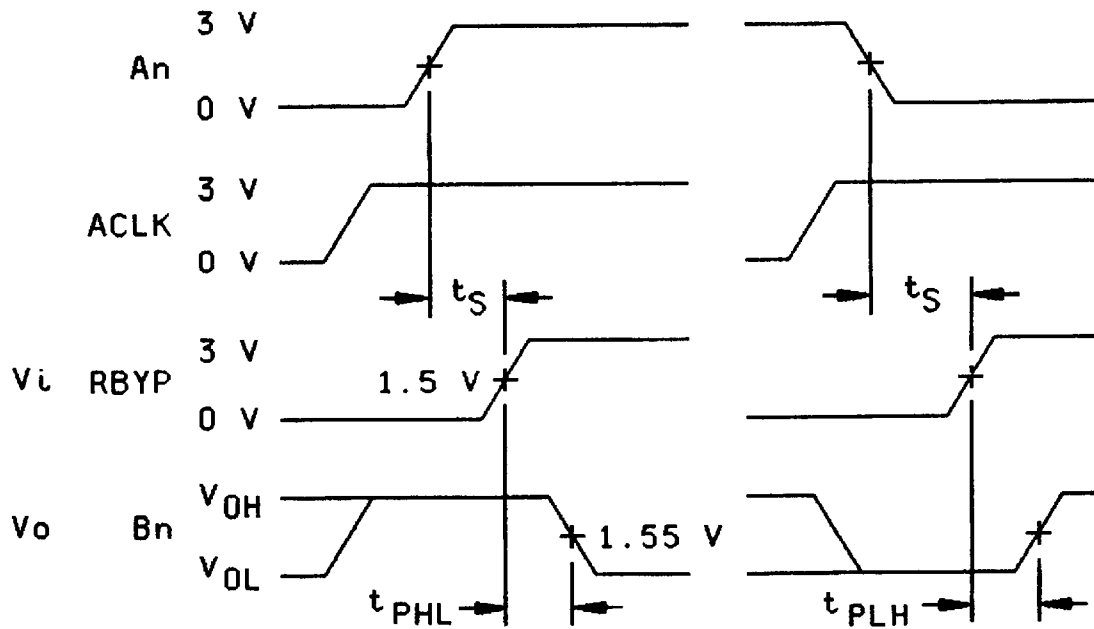
STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>	5962-95542
	REVISION LEVEL	SHEET 19

DESC FORM 193A  
 JUL 94

9004708 0009871 234



T/R to Bn ( $t_{PHL}$  and  $t_{PLH}$  only) T/R to An ( $t_{PZL}$  and  $t_{PLZ}$  only)



RBYP to Bn

FIGURE 5. Test circuits and switching waveforms. - continued

STANDARD  
MICROCIRCUIT DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-95542

REVISION LEVEL

SHEET

20

DESC FORM 193A  
JUL 94

9004708 0009872 170

4.2 Screening. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device class M.

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.

(2)  $T_A = +125^\circ\text{C}$ , minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.

b. Interim and final electrical test parameters shall be as specified in table II herein.

c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.

4.4.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. For device class M, subgroups 7 and 8 tests shall be sufficient to verify the truth table. For device classes Q and V, subgroups 7 and 8 shall include verifying the functionality of the device; these tests shall have been fault graded in accordance with MIL-STD-883, test method 5012 (see 1.5 herein).

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.

b.  $T_A = +125^\circ\text{C}$ , minimum.

c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		<b>REVISION LEVEL</b>	<b>SHEET 21</b>

DESC FORM 193A  
JUL 94

■ 9004708 0009873 007 ■

TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, TM 5005, table I)	Subgroups (in accordance with MIL-I-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3, 7, 8, 9, <u>1</u> / 10, 11	1, 2, 3, 7, 8, 9, 10, 11 <u>1</u> /	1,2,3,7,8,9 <u>2</u> /10, 11
Group A test requirements (see 4.4)	1, 2, 3, 7, 8, 9, 10, 11	1, 2, 3, 7, 8 9, 10, 11	1,2,3,7,8 9, 10, 11
Group C end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group D end-point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)	1	1	1

- 1/ PDA applies to subgroup 1.
- 2/ PDA applies to subgroups 1 and 7.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB, in accordance with MIL-I-38535, and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes Q and V shall be M, D, L, R, F, G, and H and for device class M shall be M and D.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-I-38535, appendix A, for the RHA level being tested. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-I-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$ , after exposure, to the subgroups specified in table II herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V.

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		REVISION LEVEL	SHEET 22

DESC FORM 193A  
JUL 94

■ 9004708 0009874 T43 ■

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.4 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5765, or telephone (513) 296-8525.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-I-38535 and MIL-STD-1331.

6.6 One part - one part number system. The one part - one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

<u>Military documentation format</u>	<u>Example PIN under new system</u>	<u>Manufacturing source listing</u>	<u>Document listing</u>
New MIL-H-38534 Standardized Military Drawings	5962-XXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply.

6.7.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.

6.7.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

<b>STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</b>	<b>SIZE A</b>		<b>5962-95542</b>
		<b>REVISION LEVEL</b>	<b>SHEET 23</b>

DESC FORM 193A  
JUL 94

■ 9004708 0009875 98T ■